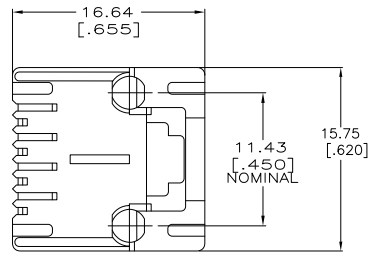
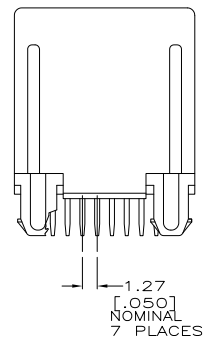
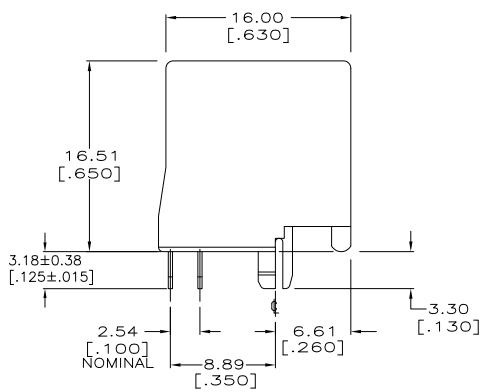
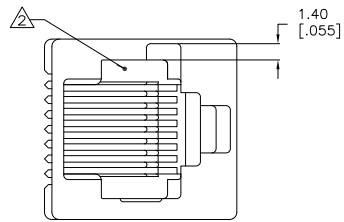
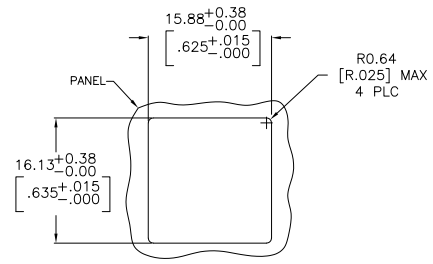


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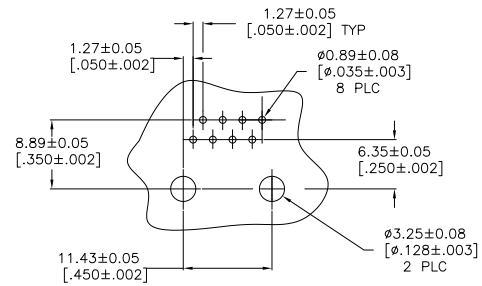
REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
B	82-07-010000				



- MATERIAL: HOUSING: PBT POLYESTER, COLOR: BLACK  
 TERMINAL: 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27μm [.000050] MIN THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] MIN THICK NICKEL UNDERPLATE
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE
- ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED



RECOMMENDED PANEL CUTOUT  
 SCALE 4:1



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT  
 COMPONENT SIDE  
 SCALE 4:1

5555799-1  
 PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	BY	APP	REV	DESCRIPTION	DATE	BY	APP
1	108-1163	114-2048	A1	00779	5555799				
DATE	BY	APP	REV	DESCRIPTION	DATE	BY	APP	REV	DESCRIPTION
114-2048	A1	00779	5555799						